



Specification
For
USB 802.11 b/g/n
WiFi Module
TWR0063
Rev. 1.0

2012-2017 Pulse(Suzhou) Wireless Products Co., Ltd

This document contain information that is proprietary to Pulse(Suzhou) Wireless Products Co., Ltd
Unauthorized reproduction or disclosure of this information in whole or in part is strictly prohibited.

Specification are subject to change without notice.

Overview

TWR0063 is 802.11 b/g/n 2.4G with USB2.0 interface module. It operated in ISM frequency band with low power consumption and it use highly integrated SOC chip MT7601UN with 150Mbps PHY 2.4G delivers superior WiFi output up to 16dBm.

TWR0063 provide high performance design for wireless connection with popular USB interface. It is good choose for high throughput networking and multimedia application. In addition, it also support security encryption through WPA, WPA2 ..and so on.



■ Feature

1. IEEE 802.11 b/g/n mode with support of 150Mbps PHY rate
2. IEEE 802.11 b/g/n client
3. 802.11e QoS support of WFA WMM, WMM PS
4. 802.11 d/h/k compliant
5. 1/2/3/4-wire PTA Wi-Fi / Bluetooth coexistence support
6. Supports 802.11w protected managed frame
7. Security : WFA WPA/WPA2 personal, WPS2.0, WAPI
8. Supports Wi-Fi Direct
9. USB 2.0/1.1 interface
10. Antenna: Option for IPEX-I & ChipAntenna
- 11. Support Windows XP/Vista/7/8, Linux 2.6.x and MAC OS**
12. USB 2.0/1.1 2.0-pitch 4 pin header (option)

■ Application

Desk-Top/Mini PC/Note-Book

Mobile, portable smart device

Set-top box/Media player

IP-Cam

Tablet

Blue-ray Disk

■ Property

Main Chip	Mediatek MT7601U
WiFi Standard	IEEE 802.11 b/g/n
Frequency	2.4~2.4835GHz
USB type	2.0/1.1
Modulation	OFDM/DBPSK/DQPSK/CCK
Spectrum	DSSS
TX Power	54M: 14dBm
	11M: 16 dBm
RX Sensitivity	1M: -90dBm@8% PER
	6M:-88dBm@10% PER
	11M:-85dBm @8% PER
	54M:-68dBm @10% PER
	108M:-68dBm @ 10% PER
	130M:-68dBm @ 10% PER
Operating Voltage	3.3V, (Min:3.0V, Type: 3.3V, Max:3.6V)
Temperature	Operating:-5°C ~ 60°C Storage: -20°C ~ 80°C
Antenna	IPEX-I or Chip antenna
Dimension	10.8x14.7x 3.2mm

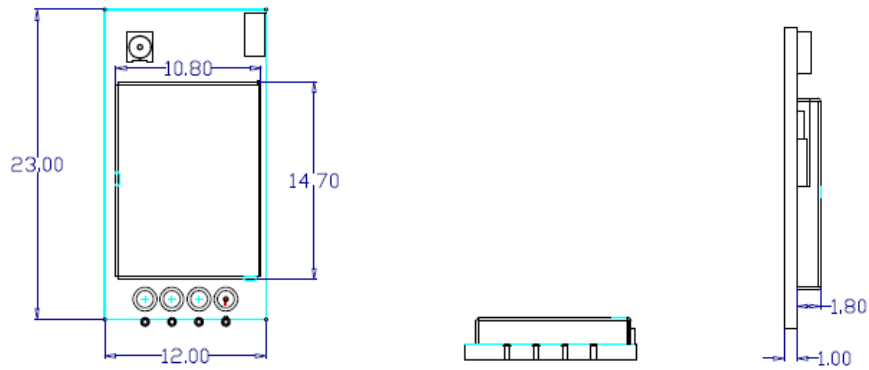
■ Platform

OS	CPU	Status
Windows (XP/Vista/Win7/Win10)	X86/X64	Ready
Linux 2.6 above	ARM, MIPS	Ready

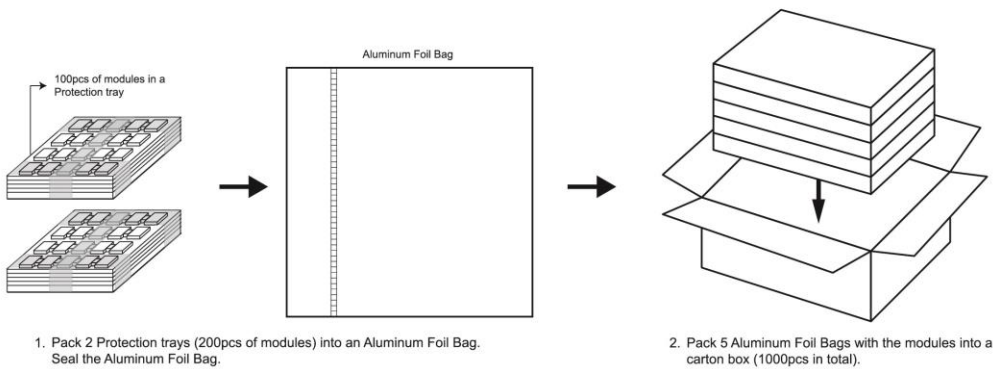
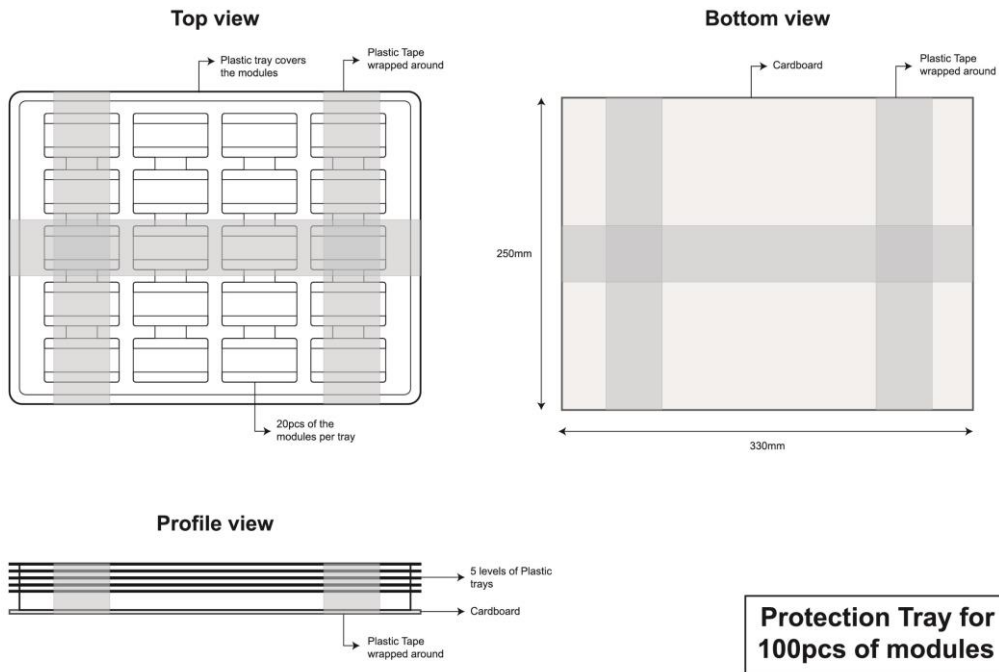
■ Pin out

Pin no.	Name	In/Out/P/G	Function
1	VDD	P	VDD Power
2	DM	I/O	USB D-
3	DP	I/O	USB D+
4	GND	G	Ground

■ Module Dimension



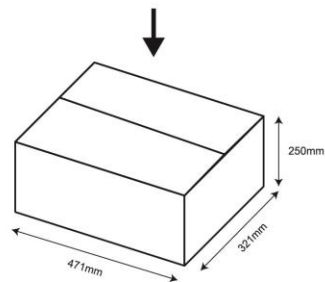
Module Packing



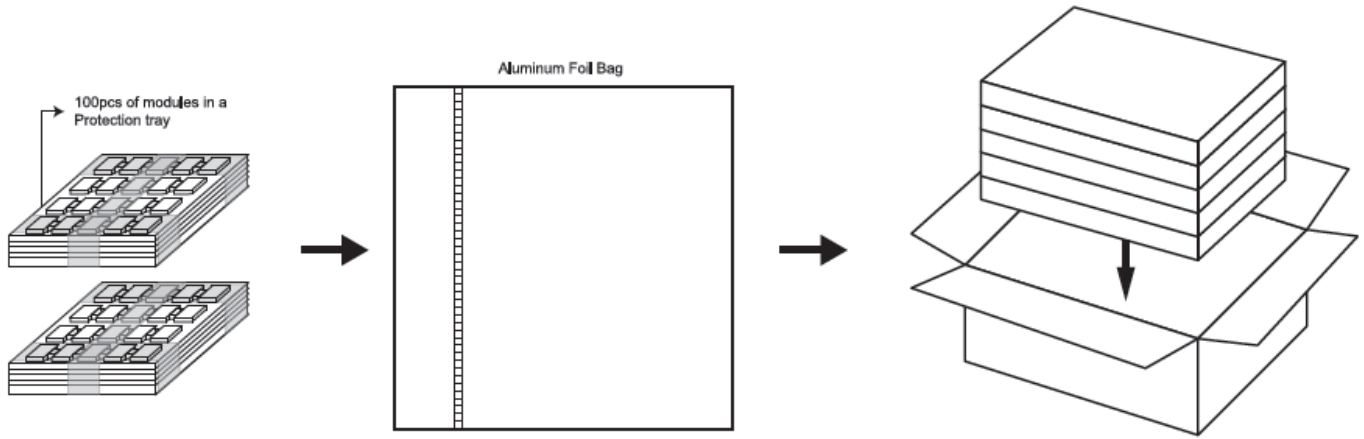
1. Pack 2 Protection trays (200pcs of modules) into an Aluminum Foil Bag. Seal the Aluminum Foil Bag.

2. Pack 5 Aluminum Foil Bags with the modules into a carton box (1000pcs in total).

Carton Box Packing Instruction



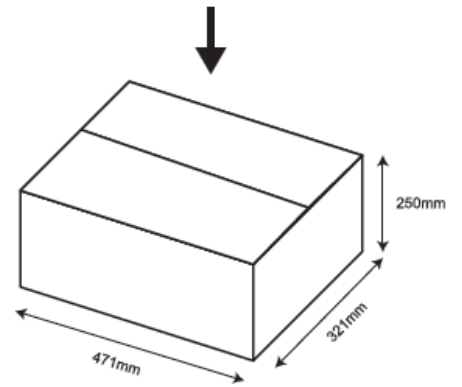
Carton Size: 471 x 321 x 250mm
Q'TY: 1000 pcs



1. Pack 2 Protection trays (200pcs of modules) into an Aluminum Foil Bag. Seal the Aluminum Foil Bag.

2. Pack 5 Aluminum Foil Bags with the modules into a carton box (1000pcs in total).

**Carton Box
Packing Instruction**



Carton Size: 471 x 321 x 250mm
Q'TY: 1000 pcs